

AMENDMENT UNDER 37 C.F.R. § 1.116
U.S. Appl. No. 09/672,776

providing a polishing composition comprising alumina fine particles containing or not containing aluminum hydrate, a polishing accelerator and water, said alumina fine particles having an α conversion ratio of from 68 to 90% and a specific surface area of from 31 to 77 m²/g, and

mechanochemically polishing a metal film on said semiconductor substrate with said polishing composition.
